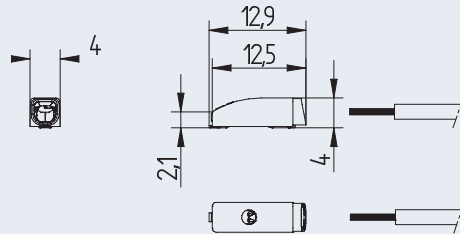
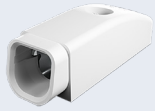


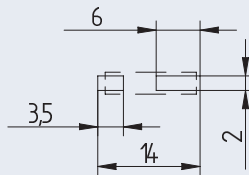
SMD Terminal blocks

46.131 · SMD Terminal block - MiniFlex



General note: It is recommended to make an electrical connection between both poles of each polarity on the solder pad.

Recommended dimensions for solder tags



SMD-Terminal block - MiniFlex with push wire contacts and contact opening function

1 pole - 46.131.2001.50

Direct insertion of solid and stranded, tinned wire ends and finely stranded conductors by using the contact opening function

Contact opening function - also for release of already inserted wires

Mounting and wiring position: PCB top side

Machine-compatible "tape-and-reel" packaging

Fixing: Lead-free reflow soldering according to DIN EN 610760-1, section 6

Material: Housing: PPA, white
Contact material: CuNi
Contact surface: hot-dipped tinned

To operate the contact opening function, we recommend the use of our tools **46.131.U802.89** and **46.131.-397.80**

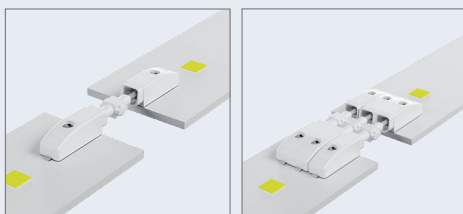
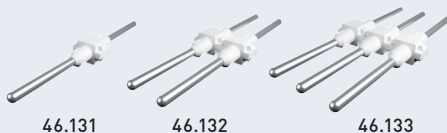
Packaging data 46.131.2001.50	
Weight per piece	0.24 g
Pieces per reel	2.650 pcs
Diameter of tape-and-reel packaging	381 mm (15")
Reel width	24 mm
Pitch distance	8 mm
Weight per reel	1.092 kg
Number of reels per carton	13 pcs
Number of SMD terminal blocks per carton	34.450 pcs
Weight per carton	15.46 kg
Carton dimensions (LxWxH)	400 x 405 x 400mm



wt. 0.24 g pkg. 2650 part no. **46.131.2001.50**

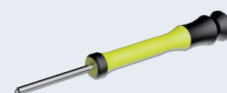
Accessories:

SMD Mini-Flex-B2B-connector. For connecting PCBs. Connectors are available in 26 mm (U701), 28 mm (U702) and 30 mm (U703) length.



Contact opening tool

For opening the contacts when using fine-stranded conductors or to remove already inserted conductors.



46.131.U802.89



46.131.-397.80

Integrated stripping function for wire ends cut but not stripped

SMD Terminal blocks

46.131 · SMD-Terminal block - MiniFlex
General technical information

Connection data	
Connection technology	Push wire contacts
Solid wires	0.20 - 0.75 mm ² , AWG 24-18
Stranded, tinned wires	0.20 - 0.5 mm ² , AWG 24-20
Stranded wires	0.20 - 0.75 mm ² , AWG 24-18
Strip length (ø < 2.1 mm)	8 +1 mm
Strip length (ø 2.1 - 2.7 mm)	9 +1 mm
Conductor entry angle to the PCB	0°
Wire release function by	Contact opening tool
Pull-out force according to DN 60999-1	
0.2 mm ²	min. 10 N
0.34 mm ²	min. 15 N
0.5 mm ²	min. 20 N
0.75 mm ²	min. 30 N
Insertion force	max. 10 N

Geometrical data	
Pin spacing	4 mm / 0.16 inch
Width	4 mm / 0.16 inch
Height	4 mm / 0.16 inch
Depth	12.9 mm / 0.51 inch
Diameter of tape-and-reel packaging	381 mm (15")
Reel width	24 mm
Pitch distance	8 mm
Packaging unit tape-and-reel	2.700 tbc
Packaging unit cardboard	35.100 (13 reels) tbc

Material data	
Insulating material group	I
Insulating material	PPA, white
PTI	600
Flammability class, based on UL 94	V0
Contact material	CuNi
Contact surface	hot-dipped tinned

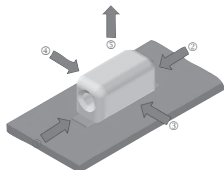
Mechanical data	
Mounting position	PCB top side
Mounting type	Lead-free reflow soldering

Temperature data	
Marginal temperatures	-40 °C to + 150 °C
Ambient temperature	-40 °C to + 105 °C
T-classification according to IEC 60998-1 para. 12	120°

Rated data according to IEC / EN 60947-7-4 (IEC/EN 60664-1)	
Rated voltage (III / 3)	63 V
Rated impulse voltage (III / 3)	2.5 kV
Rated voltage (III / 2)	160 V
Rated impulse voltage (III / 2)	2.5 kV
Rated voltage (II / 2)	320 V
Rated impulse voltage (II / 2)	2.5 kV
Rated current	9 A

Rated data according to UL 1977	
Rated voltage UL 1977	320 V
Rated current UL 1977	9 A

Country specific certificates	
VDE ENEC	EN 60947
UL	cURus, File No. E-365006

Shear forces according to IEC 62137-1-2: 2007. These values are maximum values that apply only for impuls, not for continuous load.	
Direction 1 + 2 shear force along	50
Direction 3 + 4 shear force across	20
Direction 5 pull-off force	20

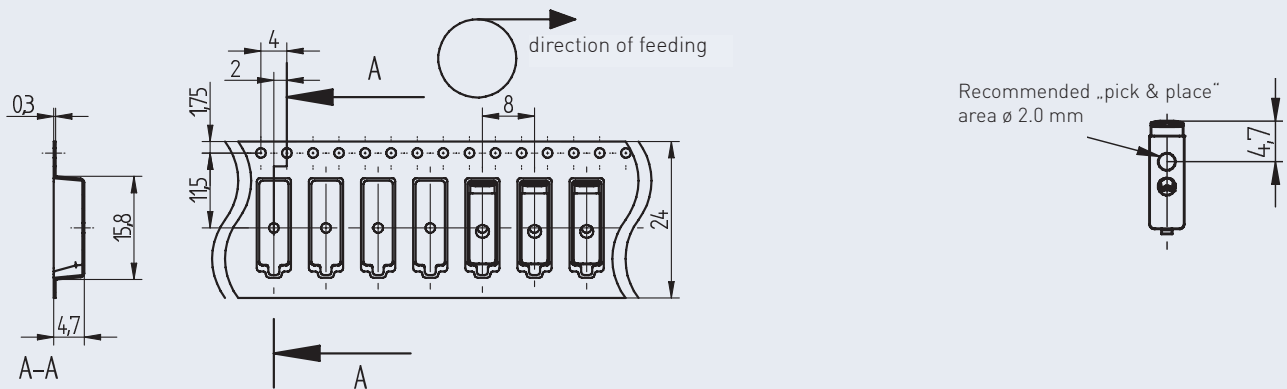
SMD Terminal blocks

46.131 · SMD-Terminal block - MiniFlex
Instructions for processing

Instructions for soldering process

Suitable for leadfree-reflow-profiles according to DIN EN 61760-1 respective DIN EN 60068-2-58 up to peak-temperature of max. 260°C.
Due to different application-specific parameters (component arrangement and alignment, soldering system, solder paste), it is recommended to use test runs to determine a suitable profile under production conditions.

Depending on the SMD soldering process and associated parameters a minor discoloration might occur. However, this will not influence the functionality.



Storage time	Solderability up to 6 months when stored between -5°C and +40°C and rel. humidity between 10...60% r H. After a storage time of 6 months, solderability has to be checked according to J-STD-002D or DIN EN 60068-2-58:2016.
max. allowed number of reflow-processes	3
Reflow-profile	Reflow-profile (lead-free)
Solderability	Solderability of components is checked by wetting test according to J-STD-002D
Assembly method	SMD, according to drawing
Recommended solder stencil thickness	100 - 150 µm (recommendation BJB 150)